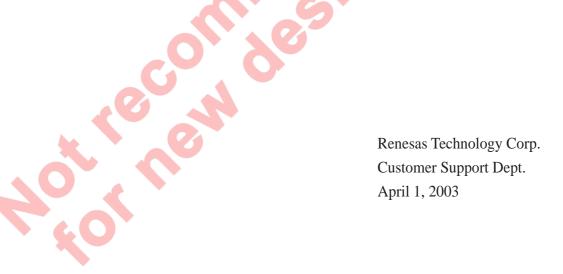
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# 2SA1468

Silicon PNP Epitaxial

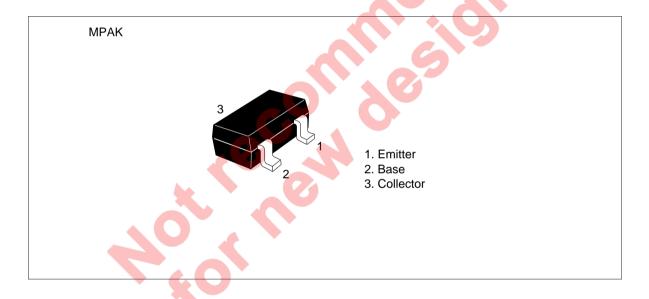


ADE-208-1018 (Z) 1st. Edition Mar. 2001

## **Application**

High voltage amplifier

#### Outline



# 2SA1468

## **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\text{CBO}}$	-180	V
Collector to emitter voltage	$V_{\text{CEO}}$	-180	V
Emitter to base voltage	$V_{EBO}$	<b>-</b> 5	V
Collector current	I <sub>c</sub>	-100	mA
Collector power dissipation	P <sub>c</sub>	150	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

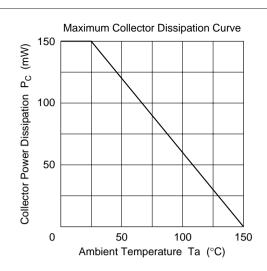
#### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

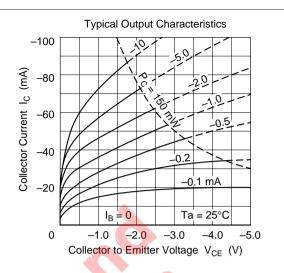
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-180	-		V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-180	4	_	V	$I_C = -0.5 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5		8	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
DC current transfer ratio	h <sub>FE</sub> *1	100	-	320		$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}^{*2}$
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	_	1/	-0.5	V	$I_{\rm C} = -30 \text{ mA}, I_{\rm B} = -3 \text{ mA}^{*2}$
Base to emitter voltage	$V_{BE}$	-0	<del>-</del>	-1.0	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Gain bandwidth product	f⊤	A	200	_	MHz	$V_{CE} = -12 \text{ V}, I_{C} = -10 \text{ mA}$
Collector output capacitance	Cob		3.5	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

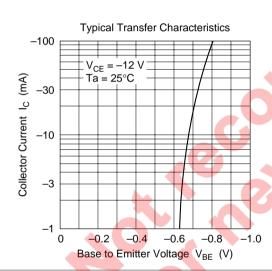
Notes: 1. The 2SA1468 is grouped by  $h_{FE}$  as follows.

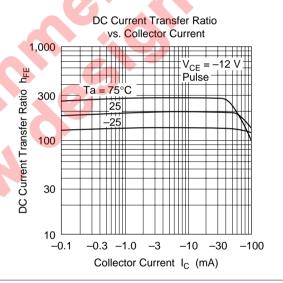
2. Pulse test

Grade	В	C
Mark	INB	INC
h <sub>FE</sub>	100 to 200	160 to 320

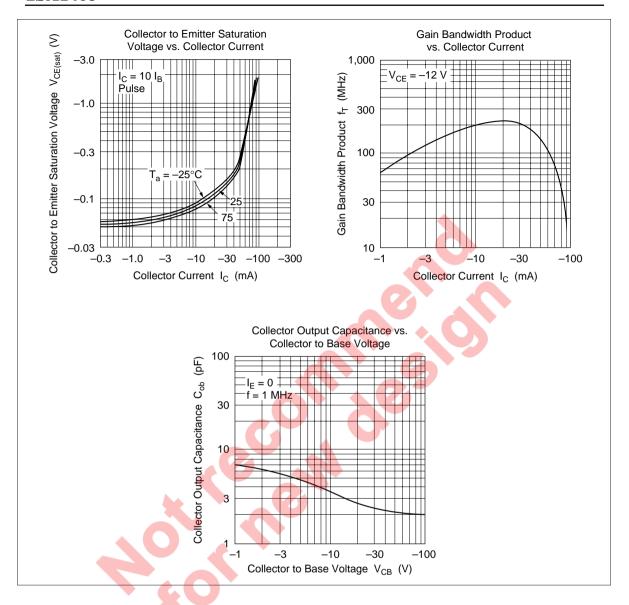




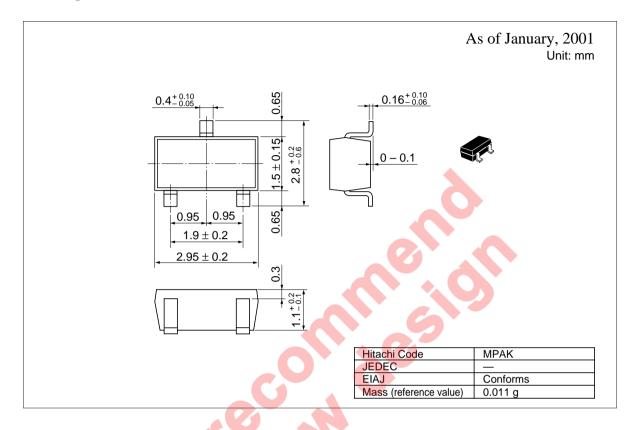




3



# **Package Dimensions**



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